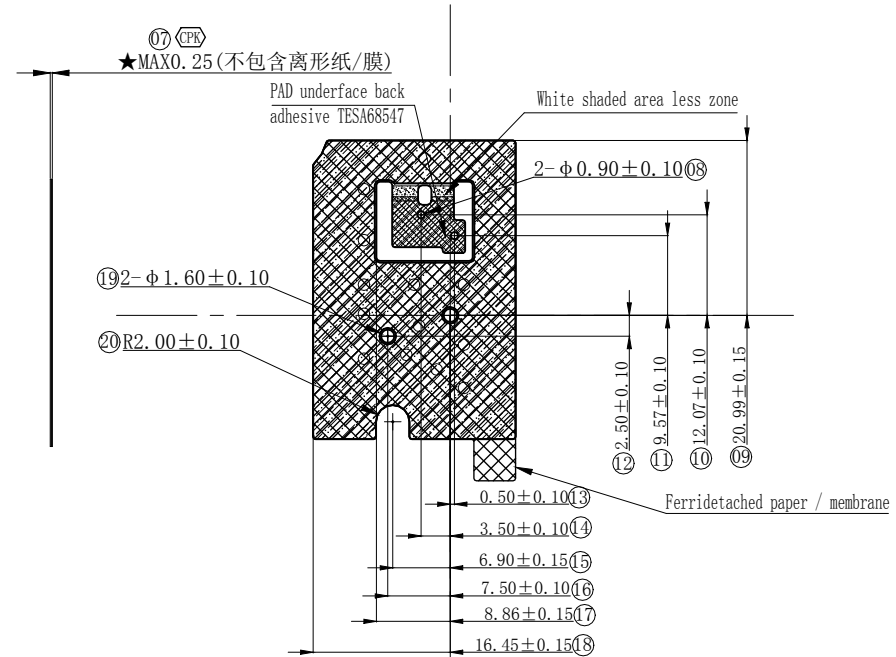
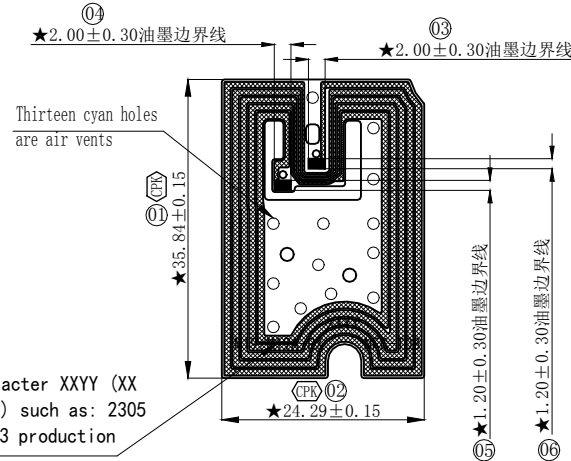


Secret drawing file

Version	Mark	Modify Content	Sign	Date
T08		P1.1 Trial production map file	zhang xing	2023.02.20
T08		Open mode map file (P1.1 Trial production map file)	zhang xing	2023.02.20
V01		Volume version upgrade V01 (screen the customer for certification)	zhang xing	2023.03.14



Front (line ink gilded)

Back (ferrite backing paper / film free area FPC backing paper)

Technical requirement:

- Side A represents the FPC laying copper wire covering the ink or cover film part, and side B represents the back collagen adhesive paper part;
- "★" Size is key size, "CPK" Need to make CPK size, "()" Is the actual size, "△" For design changes; Refer to the tolerance table for tolerances not noted;
- The surface is clean, no dirt, no copper exposed, falling off and other defects;
- The white line is the largest shape of FPC, The orange wire is the antenna patter; The blue line is the release paper cutting line, The red line is the antenna change mark; Gilded area, Adhesive area, Torn bit for release paper;
- Meet the salt spray test / adhesion test and other related reliability tests, according to our internal RX-WI-QAC-014 reliability test standards are implemented and all materials comply with our company RX-WI-QAC-008, all materials required at the same time Compliance with environmental protection RoHS2.0 and Reach requirements;
- Single-piece PE bag plus foam box packaging;
- Product packaging must be clean, tidy, packaging process Product dirt is not allowed.
- This profile is a trade secret and is limited to specified individuals or groups Weaving shall not be disclosed to any third party without permission.

1.FPC golden finger face

2.Ferrite

Dimension Tolerance Table	
Outline	±0.20
Via Hole Diam	±0.10
Via Hole Center to Outline	±0.15
Via Hole Pitch	±0.15
Ink to Trace	±0.30
Reinforcement or adhesive back to outline	±0.35

2	Ferrite	M002B0311M10001	Ferric oxide model: magnetic permeability 150 ± 10% T=0.14MM	1
1	FPC	M002B0301M10001	Single panel, black ink, electrolytic copper, PI half-to-half base material back glue large face crystal hua MTM303 back glue, PAD face: TESA68547, 2 μm ≤ Ni ≤ 6 μm, Au ≥ 0.1 μm	1
Item	Part Name	Part Number	Material description	Q'TY

PROJECT NAME	SB03			M E	zhang xing	Date	2023.03.14
Part Name	SB03 NFC Antenna finished product			R F	yangjiecheng	Date	2023.03.14
P/N	F002B0303M10001			CHECK	yang fei	Date	2023.03.14
VERSION	V01	SIZE	A4	 KunShan INNOWAVE Communication Technology Co.Ltd			
SCALE	FIT	THIRD ANGEL PROJECTION					
UNIT	MM						